

## General Description

The MY2310 is the high cell density trenched N-CH MOSFET, which provides excellent  $R_{DS(ON)}$  and efficiency for most of the small power switching and load switch applications.

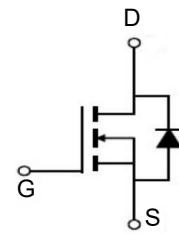
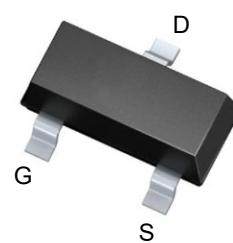


## Features

$V_{DSS}$	60	V
$I_D$	3	A
$R_{DS(ON)}(\text{at } V_{GS}=10\text{V})$	75	$\text{m}\Omega$
$R_{DS(ON)}(\text{at } V_{GS}=4.5\text{V})$	85	$\text{m}\Omega$

## Application

- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY2310	SOT-23	MY2310	3000

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		60	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	3	A
		$T_A = 100^\circ\text{C}$	2	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		12	A
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	1.5	W
$R_{eJA}$	Thermal Resistance, Junction to Ambient		83	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

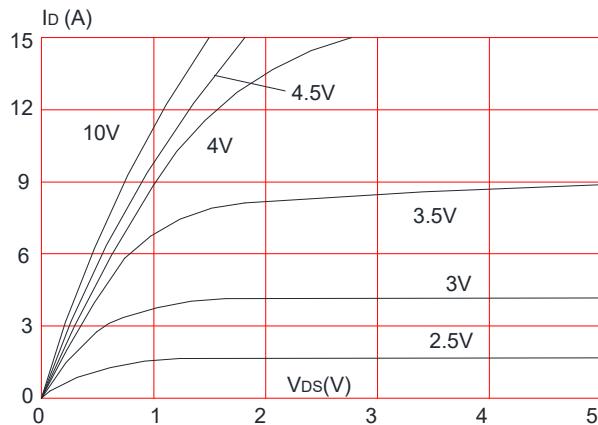
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	60	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\mu\text{A}$	1.0	1.4	2.0	V
$R_{\text{DS}(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=3\text{A}$	-	75	100	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=2\text{A}$	-	85	120	
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	-	350	-	pF
$C_{\text{oss}}$	Output Capacitance		-	29	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	23	-	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=30\text{V}$ , $I_D=3\text{A}$ , $V_{\text{GS}}=10\text{V}$	-	9	-	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	1.5	-	nC
$Q_{\text{gd}}$	Gate-Drain("Miller") Charge		-	2	-	nC
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=30\text{V}$ , $I_D=2\text{A}$ , $R_L=1\Omega$ , $R_{\text{GEN}}=3\Omega$ , $V_{\text{GS}}=10\text{V}$	-	5	-	ns
$t_r$	Turn-on Rise Time		-	7	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	37	-	ns
$t_f$	Turn-off Fall Time		-	22	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_s$	Maximum Continuous Drain to Source Diode Forward Current	-	-	3	A	
$I_{\text{SM}}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	12	A	
$V_{\text{SD}}$	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=3\text{A}$	-	-	1.2	V
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}$ , $I_F=3\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	20	-	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge		-	11	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

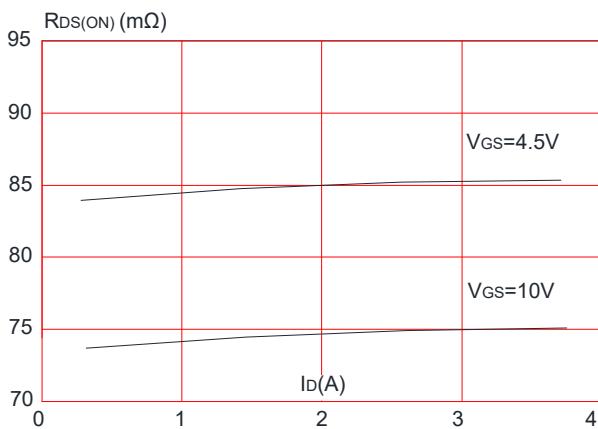
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

### Typical Electrical and Thermal Characteristics

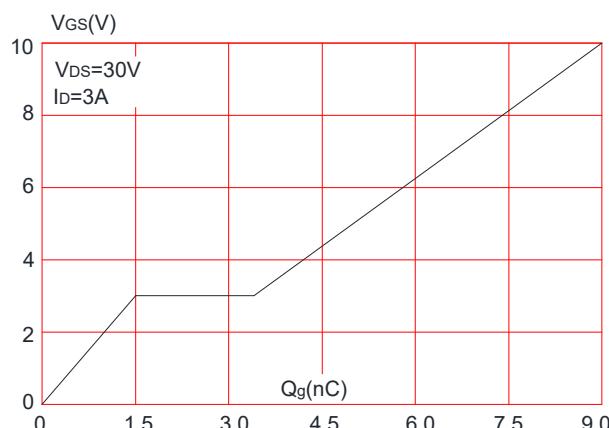
**Figure 1:** Output Characteristics



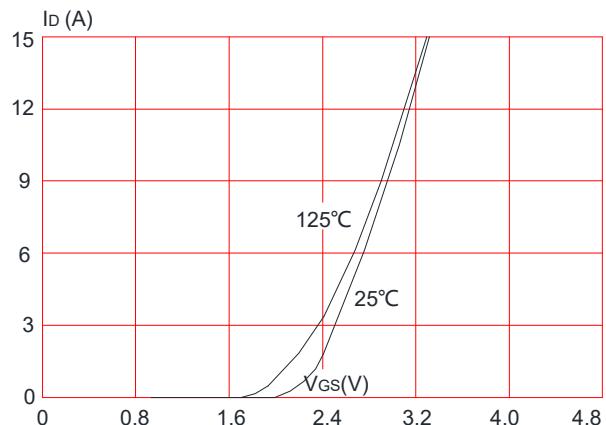
**Figure 3:** On-resistance vs. Drain Current



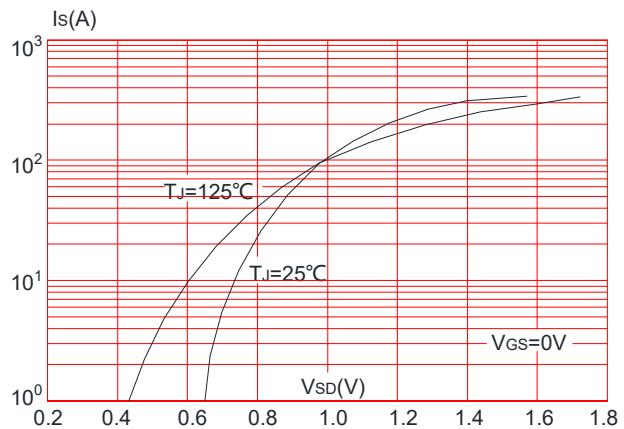
**Figure 5:** Gate Charge Characteristics



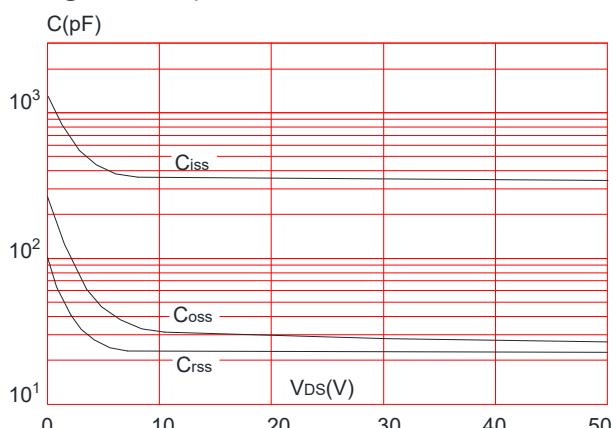
**Figure 2:** Typical Transfer Characteristics



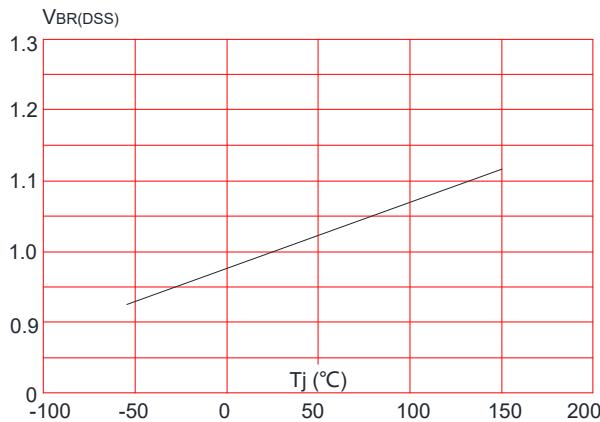
**Figure 4:** Body Diode Characteristics



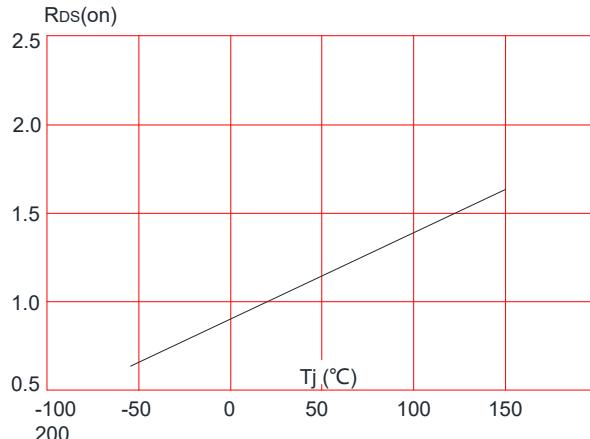
**Figure 6:** Capacitance Characteristics



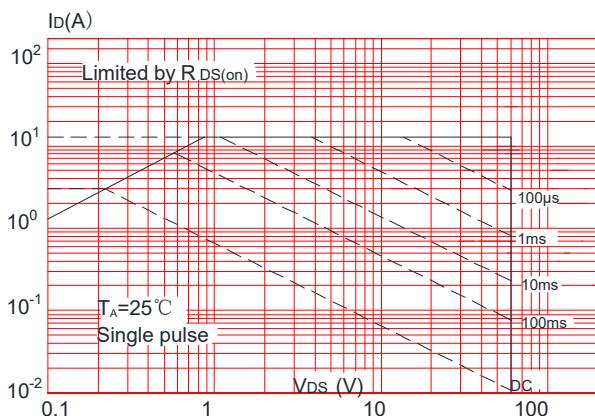
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



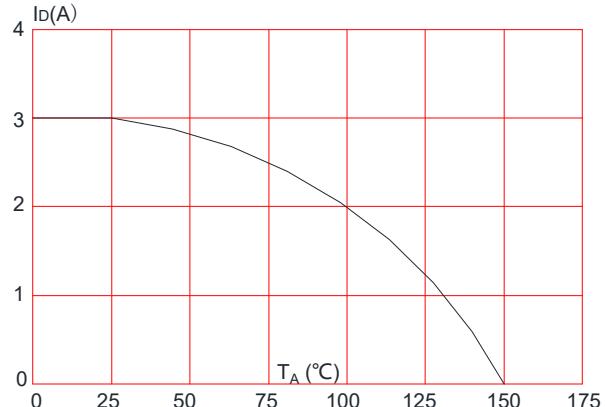
**Figure 8:** Normalized on Resistance vs. Junction Temperature



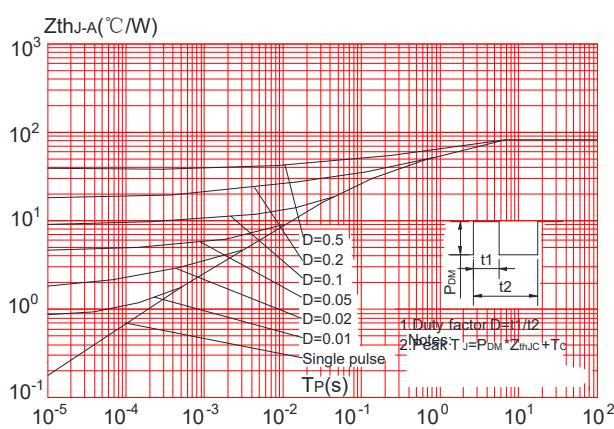
**Figure 9:** Maximum Safe Operating Area



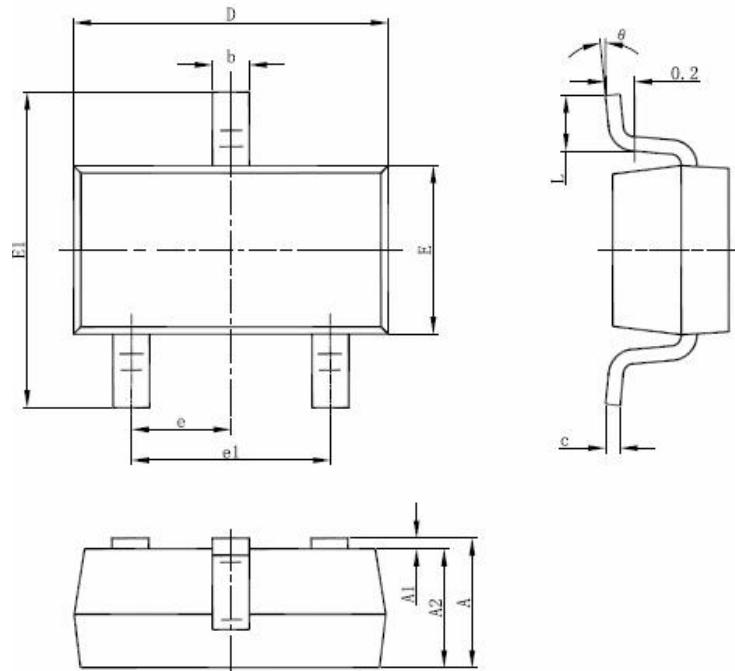
**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Package Mechanical Data-SOT-23**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°